State of the Art, Inc. M55342/12 Thin Film Chip Resistor

• Tolerances to ± 0.1%

-55° C to +150° C

terminations

Operating temperature range :

Pretinned (Sn60) nickel barrier

0603 Size, Surface Mount, Solderable

PROTECTIVE ENCAPSULANT

WRAPAROUND 99.6% ALUMINA CHIP **TERMINATIONS** PRFTINNED

PERFORMANCE CHARACTERISTICS

PRECISION

THIN FILM

RESISTOR

< 25 ppm ±0.02%

±0.02%

±0.02%

±0.02%

±0.03%

±0.03%

See Chart

5.6Ω - 270KΩ 0.1%,1%, 2%, 5%,10% Resistance Range(1) 70 mW Maximum Power

Maximum Voltage 50 Volts **ENVIRONMENTAL PERFORMANCE (2)**

TCR (-55 to +125 °C in ppm/°C) Thermal Shock Low Temperature Operation Short-time Overload **Resistance to Bonding Exposure** Moisture Resistance High Temperature Exposure Life

Tolerances

0.1% tolerance is 100 ohms to 267KΩ
 Typical Resistance change, the maximum is the same as MIL-PRF-55342. Test methods are per MIL-PRF-55342.

Solderability: Solder coating compatible with Sn60, 62 or 63 solders, provides good wetting with all types of solder attachment. All product is tested IAW Mil-Std-202, method 208, including 8 hour steam aging.

PART NUMBERING

M55342 H 12B 100D R

PRODUCT LEVEL DESIGNATOR* M: 1% per 1000 hrs. R: 0.01% per 1000 hrs. P: 0.1% per 1000 hrs T: Space Level C: Non - ER RESISTANCE AND TOLERANCE CODE Three significant digits, with a letter indicating the decimal location, and the tolerance, and the value range (Ω,ΚΩ,ΜΩ) A:0.1%Ω D:1 À: 0.1% Ω D: 1% Ω B: 0.1%KΩ E: 1%KΩ C: 0.1%MΩ F: 1%MΩ G: 2% Ω Η: 2%Κ Ω .l: 5% Ω M: 10% Ω Κ: 5%ΚΩ Ν: 10%ΚΩ L: 5%ΜΩ Ρ: 10%ΜΩ Τ: 2%ΜΩ TCR

E: ±25 ppm H: ±50 ppm K: ±100 ppm

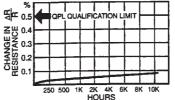
PRODUCT LEVELS

All product levels are based on the same design as our "R" level failure rate Established Reliability part. Level C is a Non-Established Reliability part requiring no group A, B or C testing. Established Reliability (failure rates based on life testing) product levels M,P, and R are subject to group A, B and C testing per MIL-PRF-55342. Space product level T requires group A and B tests including 100% power conditioning.

CURRENT NOISE 31.6 f

OISE (uVN **HOISE**

TYPICAL LIFE TEST PERFORMANCE



FEATURES

TEMPERATURE RISE DEGREES CABOVE AMBIENT

8

6

100

80 60

- TCR's to ± 25 ppm
 Suitable for solder reflow, vapor

POWER DISSIPATION

POWER DISSIPATION (WATTS)

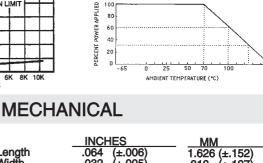
POWER DERATING

FIBER EPOX

BOARD

BOARD

phase, or wave solder attachment



Length	.064 (±.006)	1.626 (±.152)
Width	.032 (±.005)	.813 (±.127)
Thickness	.010033	.254838
Top Term.	.012 - (±.005) .015 - (±.005)	.305 - (±.127)
Bottom Term.	.015 - (±.005)	.305 - (±.127) .381 - (±.127)
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Approx. Weight .0022 grams

PACKAGING

Two packaging options are available:

Waffle Pack - (100 per Tray Max.) Tape & Reel - (5000 per 7" Inch Reel Max.)

OPTIONS

Termination type wraparound style (pretinned with a Ni barrier), and type W (wire bondable) are available. Also available in thick film MIL-PRF-55342 characteristic K & M. SOTA offers a full line of component parts in the 0603 size including Standard Grade, High-Reliability (customer specified testing), and zeroohm jumpers.

STATE OF THE ART, INC. 2470 Fox Hill Road, State College, PA 16803-1797 Phone (814) 355-8004 Fax (814) 355-2714 Toll Free 1-800-458-3401 Where Quality Isn't a Goal...It's Our Tradition

10/26/00

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